

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV6001IDCKR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV6001IDCKR	SN	Level-2-260C-1 YEAR	Ext-Mfg	DCK 5	1.25x2x0.9	6.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.010463	95.152783	951528	0.154903	1549
Precious Metals	Gold	7440-57-5	0.000082	0.745726	7457	0.001214	12
Precious Metals	Palladium	7440-05-3	0.000451	4.101491	41015	0.006677	67
Sub-Total			0.010996	100	1000000	0.162794	1628
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.030324	80	800000	0.448943	4489
Thermoplastics	Epoxy	85954-11-6	0.007581	20	200000	0.112236	1122
Sub-Total			0.037905	100	1000000	0.561179	5612
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	2.806838	96.787484	967875	41.554891	415549
Copper and Its Alloys	Iron	7439-89-6	0.06815	2.349999	23500	1.008952	10090
Copper and Its Alloys	Phosphorus	7723-14-0	0.002393	0.082517	825	0.035428	354
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000145	0.005	50	0.002147	21
Precious Metals	Silver	7440-22-4	0.01885	0.65	6500	0.279072	2791
Zinc and Its Alloys	Zinc	7440-66-6	0.003625	0.125	1250	0.053668	537
Sub-Total			2.900001	100	1000000	42.934158	429342
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0725	100	1000000	1.073354	10734
Sub-Total			0.0725	100	1000000	1.073354	10734
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	3.170788	86.850013	868500	46.943126	469431
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.018254	0.499989	5000	0.270248	2702
Other Plastics and Rubber	Carbon Black	1333-86-4	0.005476	0.149991	1500	0.081072	811
Thermoplastics	Epoxy	85954-11-6	0.45636	12.500007	125000	6.756354	67564
Sub-Total			3.650878	100	1000000	54.050799	540508
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.082251	100	1000000	1.217716	12177
Sub-Total			0.082251	100	1000000	1.217716	12177
Total			6.754531			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.